

**Amendments to the Specification:**

**Please replace the paragraph bridging pages 12 and 13 with the following amended paragraph:**

For inorganic photovoltaic devices, series connection is not particularly disadvantageous. However, due to the high series resistance of the organic photovoltaic devices noted above, a series configuration is undesirable for power applications due to the reduced efficiency. Forrest, Chem. Rev. 1997 reported that high series resistance in organic solar cells leads to space-charge build-up as power levels are raised with increasing incident light intensity. This leads to degradation of the photocurrent,  $I_{\max}$ , effectively reducing the fill factor and therefore the efficiency. Moreover, what is believed to be the only previously disclosed organic solar cell with more than one photovoltaic subcell was a tandem, i.e., two PV subcells, with the subcells connected in series. See *Effect of Thin Gold Interstitial-layer on the Photovoltaic Properties of Tandem Organic Solar Cell*, Hiramoto, M. ; Suezaki, M. ; Yokoyama, M ; *Chemistry Letters* 1990, 327 (hereinafter "Hiramoto"). Referring to Fig. 2D, substrate 2D01 is glass ; 2D02 is ITO; 2D03 is Me-PTC (500 Å); 2D04 is H<sub>2</sub>Pc (700 Å); 2D05 is Au ( <30 Å); 2D06 is Me-PTC (700 Å); H<sub>2</sub>Pc (700 Å) ; and 2D07 is Au (200 Å). This device has the subcells electrically connected internally and in series, thus avoiding the problem of devising a means to make external contact to an electrode within the middle of a stack of organic semiconducting material. Hiramoto's organic tandem devices have just two electrodes: one on top and bottom used to make external connections plus ~~charge-transfer~~ recombination layer 2D05 which electrically "floats" between the two subcells [[""]]. Only one of the electrodes, bottom ITO layer 2D02 was transparent. Top Au layer 2D07 was 200 Å thick and therefore nontransparent. Further, for the reasons noted above, series connection is not an optimal configuration in stacked organic photovoltaic devices for high power applications.